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**NEWS RELEASE
FOR IMMEDIATE RELEASE**

**S.E.C. INTRODUCES REVALPHA; NEW THERMAL RELEASE
DICING TAPE MADE BY NITTO**

MOORPARK, California, U.S.A., July 28, 2006 – Semiconductor Equipment Corporation of Moorpark, California introduces a new product in their NittoDenko line of dicing tapes called Revalpha.

Revalpha is a unique alternative to current methods of holding down material during the dicing process. Methods like wax, glue or standard dicing tapes can leave a sticky residue, which is hard to clean. Even UV curable tapes maintain a small amount of adhesion. Revalpha's special adhesive formula reduces to practically "zero" when heat is applied making the handling of sensitive and delicate parts safer and more efficient. Heat can be applied by hot air dryer, hot plate or IR lamp. There are four types of tape with thermal release temperatures of 90, 120, 150 and 170 degrees C. They can be easily applied with roller pressure or autoclave procession and maintains a constant adhesion level for storage prior to curing allowing flexibility in process management.

Revalpha has: excellent adhesion with easy release by heating, various thermal release adhesion grades, 4 types of release temperatures and available in rolls, labelers and sheets depending on application.

(Photo enclosed)